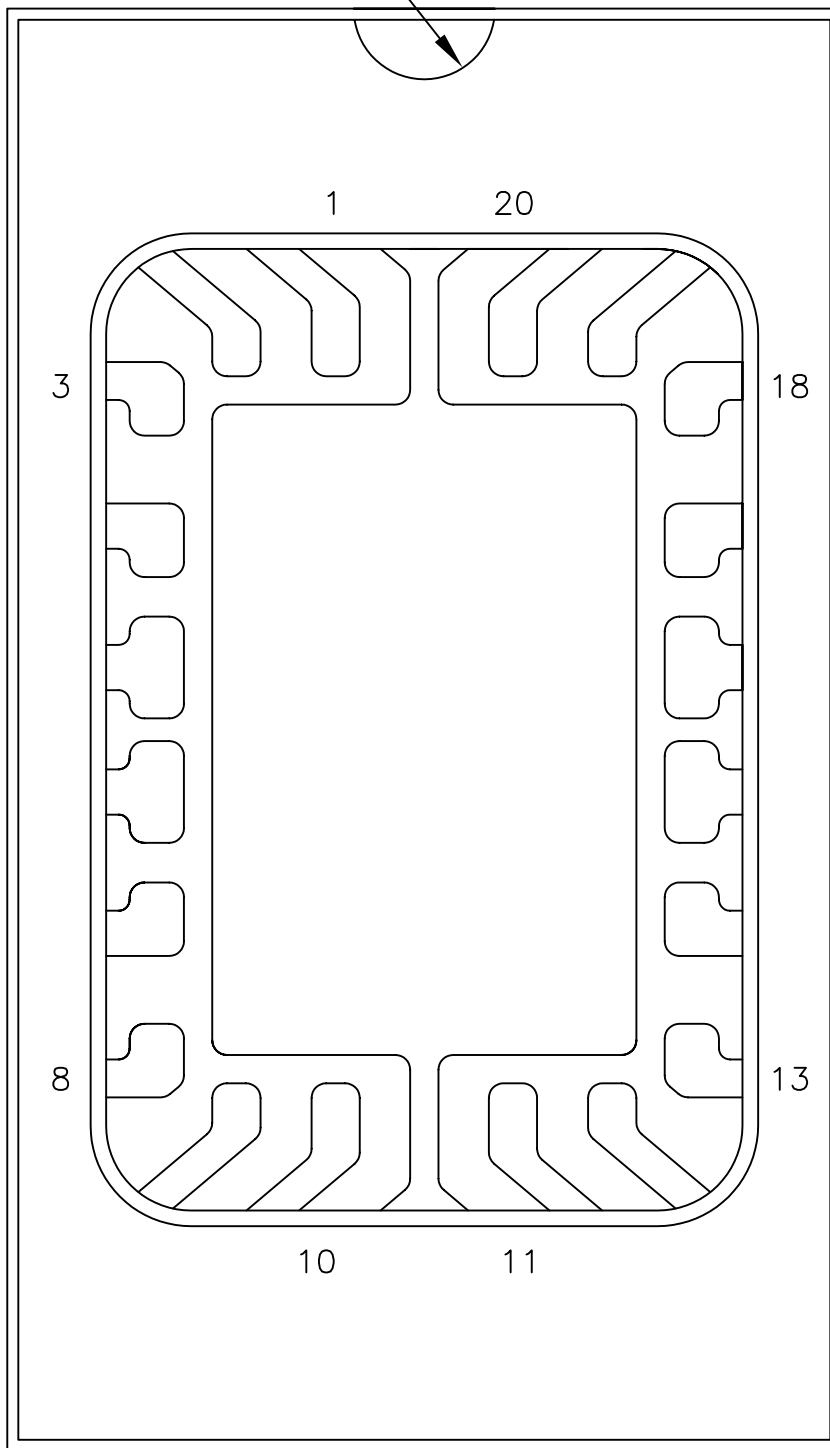


PIN #1 IDENTIFIER



DEVICE TYPE:

CUSTOMER:

WIRE TYPE/  
SIZE:

DIE  
SIZE:

NO. OF  
WIRES:



THIRD ANGLE  
PROJECTION

REVISIONS

UNLESS OTHERWISE SPECIFIED  
DIMENSIONS ARE IN INCHES.  
DO NOT SCALE DRAWING

ECN NO.

DATE

DESCRIPTION

APPROVED

10514

11/2/05

PRODUCTION RELEASE

D.BENANDO

DRAWN  
BY W. GRIFFITTS

DATE 11/1/05

PACKAGE  
SIZE: 0.510" x 0.295"

APP  
BY P. FLASKERUID

DATE 11/1/05

DIE PAD  
SIZE: 0.220" x 0.150"

SIZE  
A

PART NO.

SOIC300-20-OP-01

REV  
2

SCALE 24X

CAD  
FILE

SOIC300-20-OP-01-B-R2.DWG

SHEET 1 OF 1

**SEMPAC, INC.**

Open-Pak™ Technologies

www.sempac.com

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PHONE: (408) 400-9002 FAX: (408) 400-9006

20 Lead 300 mils SOIC Open-Pak  
Bonding Diagram